Thick-Film Hybrid IC

# **Inverter Power H-IC** for 3-phase Motor Drive



http://onsemi.com

#### Overview

This "Inverter Power H-IC" is highly integrated device containing all High Voltage (HV) control from HV-DC to 3-phase outputs in a single small SIP module. Output stage uses IGBT/FRD technology and implements Under Voltage Protection (UVP) and Over Current Protection (OCP) with a Fault Detection output flag. Internal Boost diodes are provided for high side gate boost drive.

#### **Function**

- Single control power supply due to Internal bootstrap circuit for high side pre-driver circuit
- All control inputs and status outputs are at low voltage levels directly compatible with microcontrollers.
- A single power supply drive is enabled through the use of bootstrap circuits for upper power supplies
- Built-in dead-time for shoot-thru protection
- Having open emitter output for low side IGBTs; individual shunt resistor per phase for OCP
- Externally accessible embedded thermistor for substrate temperature measurement
- Shutdown function 'ITRIP' to disable all operations of the 6 phase output stage by external input

#### Certification

• UL1557 (File number: E339285).

#### **Specifications**

#### **Absolute Maximum Ratings** at Tc = 25°C

Parameter	Symbol	Remarks	Ratings	Unit
Supply voltage	VCC	V+ to U-, V-, W-, surge<500V *1	450	V
Collector-emitter voltage	VCE	V+ to U, V, W or U, V, W, to U-, V-, W-	600	V
Outrot sument	la.	V+,U-,V-,W-,U,V,W terminal current	±10	Α
Output current	lo	V+,U-,V-,W-,U,V,W terminal current, Tc=100°C	±7	Α
Output peak current	lop	V+,U-,V-,W-,U,V,W terminal current, P.W.=1ms	±20	Α
Pre-driver voltage	VD1,2,3,4	VB1 to U, VB2 to V, VB3 to W, VDD to VSS *2	20	V
Input signal voltage	VIN	HIN1, 2, 3, LIN1, 2, 3	-0.3 to VDD	V
FLTEN terminal voltage	VFLTEN	FLTEN terminal	-0.3 to VDD	V
Maximum power dissipation	Pd	IGBT per 1 channel	30	W
Junction temperature	Tj	IGBT, FRD, Pre-Driver IC	150	°C
Storage temperature	Tstg		-40 to +125	°C
Operating case temperature	Тс	H-IC case	-40 to +100	°C
Tightening torque		A screw part *3	0.9	Nm
Withstand voltage	Vis	50Hz sine wave AC 1 minute *4	2000	VRMS

Reference voltage is "VSS" terminal voltage unless otherwise specified.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 15 of this data sheet.

<sup>\*1:</sup> Surge voltage developed by the switching operation due to the wiring inductance between + and U-(V-, W-) terminal.

<sup>\*2:</sup> VD1=VB1 to U, VD2=VB2 to V, VD3=VB3 to W, VD4=VDD to VSS terminal voltage.

<sup>\*3:</sup> Flatness of the heat-sink should be less than  $-50\mu m$  to  $+100\mu m$ .

<sup>\*4:</sup> Test conditions : AC2500V, 1 second

### **Electrical Characteristics** at Tc = 25°C, VD1, VD2, VD3, VD4 = 15V

Parameter	Symbol	Conditions	Test circuit	MIN	TYP	MAX	Unit
Power output section							
Collector-emitter cut-off current	ICE	VCE = 600V	Fig. 4	-	-	100	μA
Bootstrap diode reverse current	IR(BD)	VR(BD) = 600V	Fig.1	-	-	100	μA
Collector to emitter saturation voltage	VOE(CAT)	Ic = 10A, Tj=25°C	Γ: 0	ı	1.6	2.2	V
	VCE(SAT)	Ic = 5A, Tj=100°C	Fig.2	-	1.35	-	V
Diode forward voltage	VF	IF = -10A, Tj=25°C	Fig 2	-	1.6	2.1	- V
blode forward voltage	VF	IF = -5A, Tj=100°C	Fig.3	-	1.3	-	v
Junction to case thermal resistance	θj-c(T)	IGBT	_	-	-	4	°C /W
Junction to case thermal resistance	θj-c(D)	FWD	-	-	-	5	C/VV
Control (Pre-driver) section							
		VD1,2,3 = 15V	-: .	-	0.08	0.4	
Pre-driver power dissipation	ID	VD4 = 15V	Fig.4	-	1.6	4	mA
High level Input voltage	Vin H	HIN1,HIN2,HIN3,	-	2.5	-	-	V
Low level Input voltage	Vin L	LIN1,LIN2,LIN3 to VSS	-	ı	-	0.8	٧
Logic 1 input leakage current	I <sub>IN+</sub>	VIN=+3.3V	ı	ı	100	143	μA
Logic 0 input leakage current	I <sub>IN-</sub>	VIN=0V	ı	ı	-	2	μA
FLTEN terminal sink current	IoSD	FAULT:ON / VFLTEN=0.1V	-	ı	2	-	mA
FLTEN clearance delay time	FLTCLR	From time fault condition clear	-	1.3	1.65	2	ms
CI TCNI There are also	VEN+	VEN rising	-	-	-	2.5	٧
FLTEN Threshold	VEN-	VEN falling	-	0.8	-	-	٧
ITRIP threshold voltage	VITRIP	ITRIP(16) to VSS(29)	-	0.44	0.49	0.54	V
ITRIP to shutdown propagation delay	t <sub>ITRIP</sub>		-	340	550	800	ns
ITRIP blanking time	t <sub>ITRIPBL</sub>		-	250	350	-	ns
$V_{\text{CC}}$ and $V_{\text{BS}}$ supply undervoltage protection reset	$V_{\text{CCUV+}}$ $V_{\text{BSUV+}}$		-	10.5	11.1	11.7	V
$V_{\text{CC}}$ and $V_{\text{BS}}$ supply undervoltage protection set	V <sub>CCUV-</sub> V <sub>BSUV-</sub>		-	10.3	10.9	11.5	V
$V_{\text{CC}}$ and $V_{\text{BS}}$ supply undervoltage hysteresis	V <sub>CCUVH</sub> V <sub>BSUVH</sub>		-	0.14	0.2	-	V
Thermistor for substrate temperature Monitor	Rt	Resistance between TH(27) and VSS(29)	ı	42.3	47	51.7	kΩ

Reference voltage is "VSS" terminal voltage unless otherwise specified.

Parameter	Symbol	Conditions	Test circuit	MIN	TYP	MAX	Unit
Switching Character							
Out the later of the co	t ON	Io = 10A	F: F	-	0.4	-	
Switching time	t OFF	Inductive load	Fig.5	ı	0.65	-	μs
Turn-on switching loss	Eon	Io=5A,V <sup>+</sup> =300V,		ı	130	-	μJ
Turn-off switching loss	Eoff	V <sub>DD</sub> =15V,L=650uH	Fig.5	ı	122	-	μJ
Total switching loss	Etot	Tc=25°C		1	252	-	μJ
Turn-on switching loss	Eon	Io=5A,V <sup>+</sup> =300V,		ı	156	-	μJ
Turn-off switching loss	Eoff	V <sub>DD</sub> =15V,L=650uH	Fig.5	ı	154	-	μJ
Total switching loss	Etot	Tc=100°C		ı	310	-	μJ
Diode reverse recovery energy	Erec	$I_0=5A, V^+=400V, V_{DD}=15V,$	-	ı	6.9	-	μJ
Diode reverse recovery time	Trr	L=650uH, Tc=100°C	-	ı	57	-	ns
Reverse bias safe operating area	RBSOA	Io = 20A, VCE = 450V	-	F	ull square	<del>)</del> -	-
Short circuit safe operating area	SCSOA	VCE = 400V, Tc=100°C	-	4	-	-	μs
Allowable offset voltage slew rate	dv/dt	Between U(V,W) to U-(V-,W-)	-	-50	-	50	V/ns

Reference voltage is "VSS" terminal voltage unless otherwise specified.

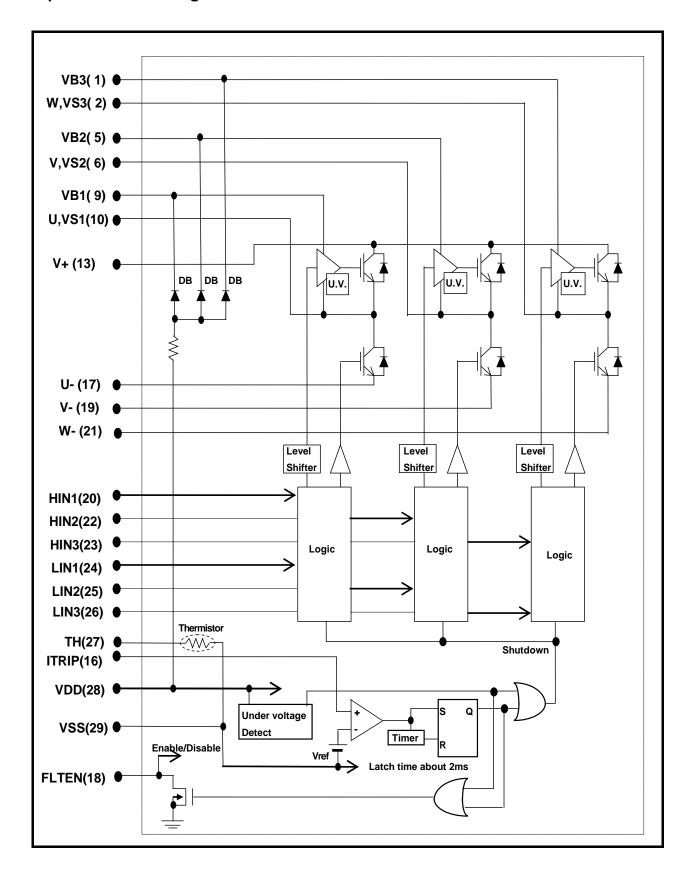
#### **Notes**

- 1. The pre-drive power supply low voltage protection has approximately 200mV of hysteresis and operates as follows.
  - Upper side : The gate is turned off and will return to regular operation when recovering to the normal voltage, but the latch will continue till the input signal will turn 'low'.
  - Lower side: The gate is turned off and will automatically reset when recovering to normal voltage. It does not depend on input signal voltage.
- 2. When assembling the H-IC on the heat sink the tightening torque range is 0.6Nm to 0.9Nm.
- 3. The pre-drive low voltage protection protects the device when the pre-drive supply voltage falls due to an operating malfunction.
- 4. When use the over-current protection with external shunt resistor, please set the current protection level to be equal to or less than the rating of output peak current (lop).

## **Module Pin-Out Description**

Pin	Name	Description
1	VB3	High Side Floating Supply Voltage 3
2	W, VS3	Output 3 - High Side Floating Supply Offset Voltage
3	-	Without pin
4	-	Without pin
5	VB2	High Side Floating Supply voltage 2
6	V,VS2	Output 2 - High Side Floating Supply Offset Voltage
7	-	Without pin
8	-	Without pin
9	VB1	High Side Floating Supply voltage 1
10	U,VS1	Output 1 - High Side Floating Supply Offset Voltage
11	-	Without pin
12	-	Without pin
13	V+	Positive Bus Input Voltage
14	-	Without pin
15	-	Without pin
16	ITRIP	Current protection pin
17	U-	Low Side Emitter Connection - Phase U
18	FLTEN	Enable input / Fault output
19	V-	Low Side Emitter Connection - Phase V
20	HIN1	Logic Input High Side Gate Driver - Phase U
21	W-	Low Side Emitter Connection - Phase W
22	HIN2	Logic Input High Side Gate Driver - Phase V
23	HIN3	Logic Input High Side Gate Driver - Phase W
24	LIN1	Logic Input Low Side Gate Driver - Phase U
25	LIN2	Logic Input Low Side Gate Driver - Phase V
26	LIN3	Logic Input Low Side Gate Driver - Phase W
27	TH	Thermistor output
28	VDD	+15V Main Supply
29	VSS	Negative Main Supply

## **Equivalent Block Diagram**



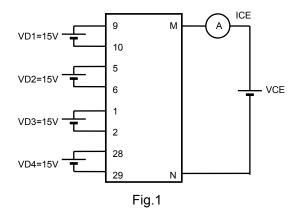
#### **Test Circuit**

(The tested phase : U+ shows the upper side of the U phase and U- shows the lower side of the U phase.)

#### ■ ICE / IR(BD)

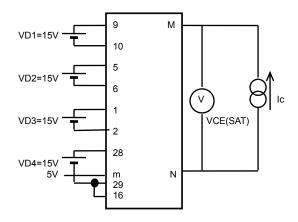
	U+	V+	W+	U-	V-	W-
M	13	13	13	10	6	2
N	10	6	2	17	19	21

	U(BD)	V(BD)	W(BD)
M	9	5	1
N	29	29	29



#### ■ VCE(SAT) (Test by pulse)

	U+	V+	W+	U-	V-	W-
M	13	13	13	10	6	2
N	10	6	2	17	19	21
m	20	22	23	24	25	26



#### ■ VF (Test by pulse)

	U+	V+	W+	U-	V-	W-
М	13	13	13	10	6	2
N	10	6	2	17	19	21

Fig.2

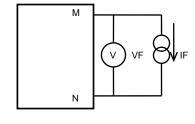


Fig.3

#### ■ ID

	VD1	VD2	VD3	VD4
M	9	5	1	28
N	10	6	2	29

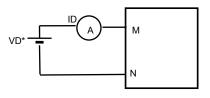
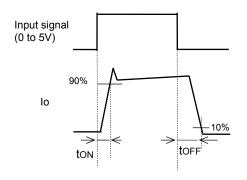


Fig.4

#### ■ Switching time (The circuit is a representative example of the lower side U phase.)



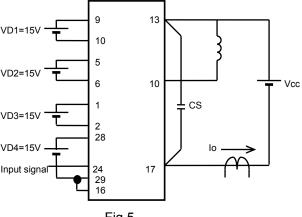
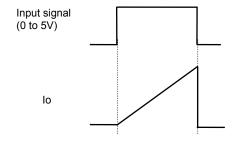
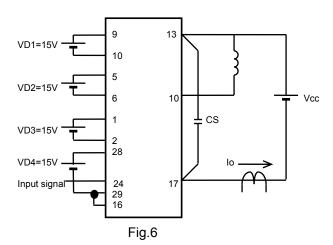


Fig.5

#### ■ RB-SOA (The circuit is a representative example of the lower side U phase.)





#### **Input / Output Timing Chart**

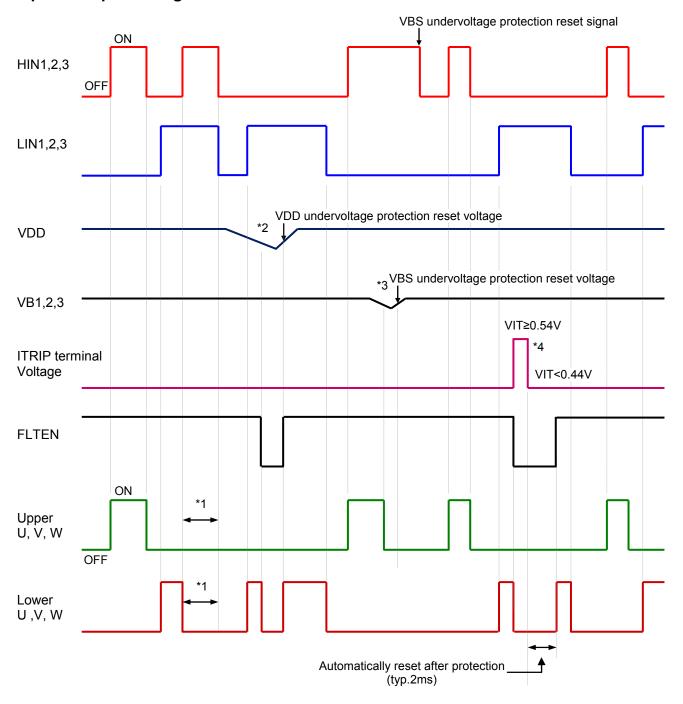
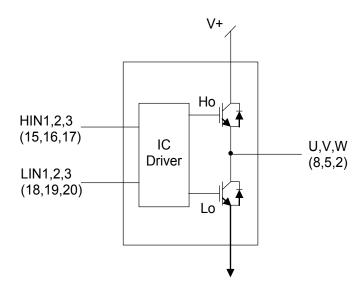


Fig. 7

- 1. \*1 shows the prevention of shoot-thru via control logic, however, more dead time must be added to account for switching delay externally.
- 2. \*2 when VDD decreases all gate output signals will go low and cut off all 6 IGBT outputs. When VDD rises the operation will resume immediately.
- 3. \*3 when the upper side voltage at VB1, VB2 and VB3 drops only the corresponding upper side output is turned off. The outputs return to normal operation immediately after the upper side gate voltage rises.
- 4. \*4 when VITRIP exceeds threshold all IGBT's are turned off and normal operation resumes 2ms (typ) after over current condition is removed.

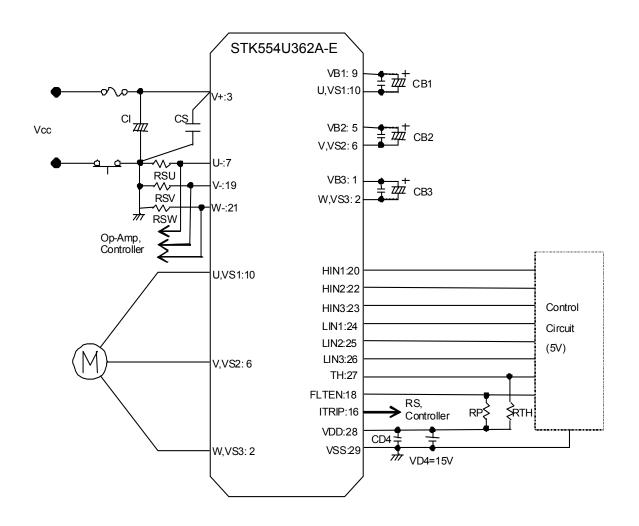
## Logic level table



FLTEN	Itrip	HIN1,2,3	LIN1,2,3	U,V,W
1	0	1	0	Vbus
1	0	0	1	0
1	0	0	0	Off
1	0	1	1	Off
1	1	Х	Х	Off
0	Х	Х	Х	Off

Fig. 8

Sample Application Circuit



#### **Recommended Operating Condition** at Tc = 25°C

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Supply voltage	vcc	V+ to U-(V-,W-)	0	280	450	V
Pre-driver	VD1,2,3	VB1 to U,VB2 to V,VB3 to W	12.5	15	17.5	.,
supply voltage	VD4	VDD to VSS *1	13.5	15	16.5	V
ON-state input voltage	VIN(ON)	HIN1,HIN2,HIN3,	3.0	-	5.0	.,
OFF-state input voltage	VIN(OFF)	LIN1,LIN2,LIN3	0	-	0.3	V
PWM frequency	fPWM		1	-	20	kHz
Dead time	DT	Turn-off to turn-on (external)	0.5	-	-	μs
Allowable input pulse width	PWIN	ON and OFF	1	-	-	μs
Tightening torque		'M3' type screw	0.6	-	0.9	Nm

<sup>\*1</sup> Pre-drive power supply (VD4=15±1.5V) must have the capacity of Io=20mA (DC), 0.5A (Peak).

#### **Usage Precaution**

- 1. This H-IC includes internal bootstrap diode and resistor. By adding a bootstrap capacitor "CB", a high side drive voltage is generated; each phase requires an individual bootstrap capacitor. The recommended value of CB is in the range of 1 to 47μF, however, this value needs to be verified prior to production. If selecting the capacitance more than 47μF (±20%), connect a resistor (about 20Ω) in series between each 3-phase upper side power supply terminals (VB1,2,3) and each bootstrap capacitor.

  When not using the bootstrap circuit, each upper side pre-drive power supply requires an external independent power supply.
- 2. It is essential that wirning length between terminals in the snubber circuit be kept as short as possible to reduce the effect of surge voltages. Recommended value of "CS" is in the range of 0.1 to 10μF.
- 3. The "FLTEN" terminal (Pin 18) is I/O terminal; Fault output / Enable input. It is used to indicate an internal fault condition of the module and also can be used to disable the module operation.
- 4. Inside the H-IC, a thermistor used as the temperature monitor for internal subatrate is connected between VSS terminal and TH terminal, therefore, an external pull up resistor connected between the TH terminal and an external power supply should be used. The temperature monitor example application is as follows, please refer the Fig.10, and Fig.11 below.
- 5. The pull-down resistor (:33k $\Omega$ (typ)) is connected with the inside of the signal input terminal, but please connect the pull-down resistor(about 2.2 to 3.3k $\Omega$ ) outside to decrease the influence of the noise by wiring etc.
- 6. As protection of H-IC to the unusual current by a short circuit etc., it recommends installing shunt resistors and an over-current protection circuit outside. Moreover, for safety, a fuse on Vcc line is recommended.
- 7. Disconnection of terminals U, V, or W during normal motor operation will cause damage to H-IC, use caution with this connection.
- 8. The "ITRIP" terminal (Pin 16) is the input terminal to shut down. When VITRIP exceeds threshold (0.44V to 0.54V) all IGBT's are turned off. And normal operation resumes 2ms (typ) after over current condition is removed. Therefore, please turn all the input signals off (Low) in case of detecting error at the "FLTEN" terminal.
- 9. When input pulse width is less than 1µs, an output may not react to the pulse. (Both ON signal and OFF signal)
  - This data shows the example of the application circuit, and does not guarantee a design as the mass production set.

#### The characteristic of thermistor

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Resistance	R <sub>25</sub>	T = 25°C	44.6	47.0	49.4	kΩ
Resistance	R <sub>125</sub>	T = 125°C	1.28	1.41	1.53	kΩ
B-Constant(25-50°C)	В		4010	4050	4091	K
Temperature Range			-40		+125	°C

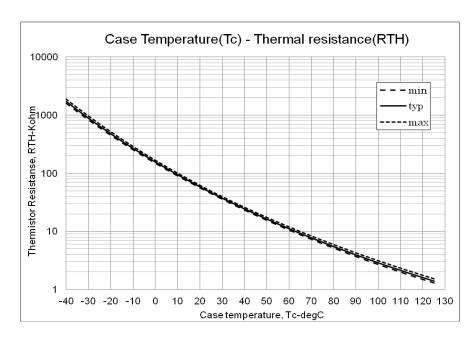


Fig.10 Variation of thermistor resistance with temperature

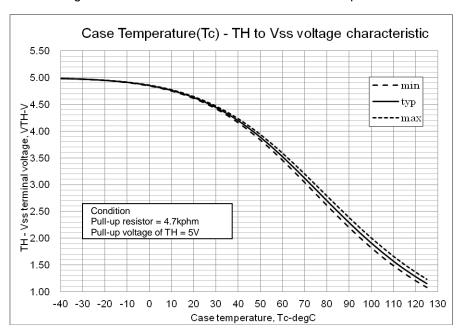


Fig.11 Variation of temperature sense voltage with thermistor temperature

#### **Maximum Phase current**

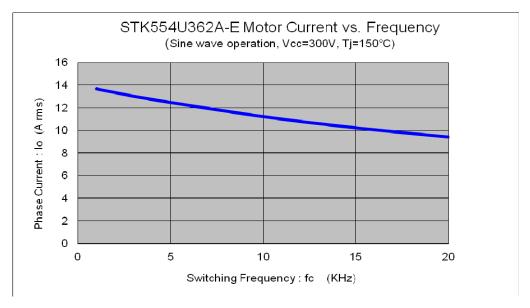


Fig.12 Maximum sinusoidal phase current as function of switching frequency at  $Tc=100^{\circ}C$ , Vcc=300V

## **Switching waveform**

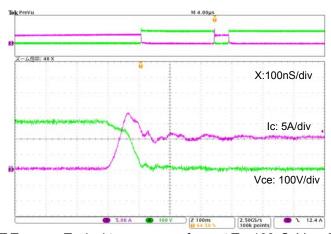


Fig. 13 IGBT Turn-on. Typical turn-on waveform at Tc=100°C, Vcc=300V, Ic=10A

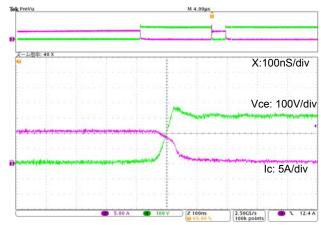


Fig. 14 IGBT Turn-off. Typical turn-off waveform Tc=100°C, Vcc=300V, Ic=10A

#### CB capacitor value calculation for bootstrap circuit

#### **Calculate condition**

Item	Symbol	Value	Unit
Upper side power supply.	VBS	15	V
Total gate charge of output power IGBT at 15V.	Qg	89	nC
Upper side power supply low voltage protection.	UVLO	12	V
Upper side power dissipation.	IDmax	400	μΑ
ON time required for CB voltage to fall from 15V to UVLO	Ton-max	-	S

## Capacitance calculation formula

CB must not be discharged below to the upper limit of the UVLO - the maximum allowable on-time (Ton-max) of the upper side is calculated as follows:

```
VBS * CB - Qg - IDmax * Ton-max = UVLO * CB
CB = (Qg + IDmax * Ton-max) / (VBS - UVLO)
```

The relationship between Ton-max and CB becomes as follows. CB is recommended to be approximately 3 times the value calculated above. The recommended value of CB is in the range of 1 to  $47\mu$ F, however, the value needs to be verified prior to production.

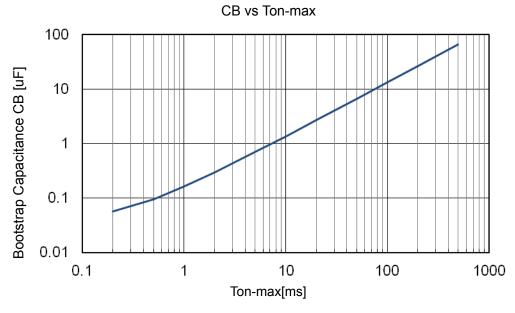


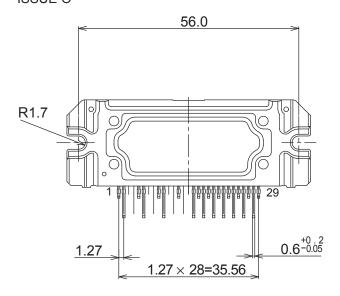
Fig.15 Ton-max vs CB characteristic

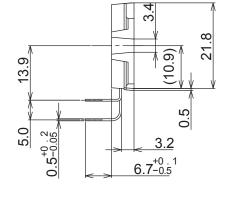
## **Package Dimensions**

(unit: mm)

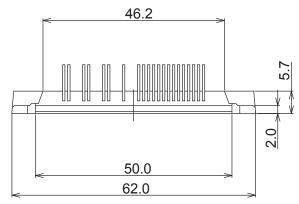
## SIP29 56x21.8

CASE 127BW ISSUE O





missing pin: 3,4,7,8,11,12,14,15



#### ORDERING INFORMATION

Device	Package	Shipping (Qty / Packing)
STK554U362A-E	SIP29 56x21.8 (Pb-Free)	8 / Tube

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